

L Number	Hits	Search Text	DB	Time stamp
2	136	novich	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:02
3	19920	robertson	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:02
4	30	velpari	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:02
5	54969	wu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:03
6	73963	novich robertson velpari wu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:03
7	163127	(fiber filament) near2 glass	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:03
8	50473	fiberglass	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:04
9	202267	((fiber filament) near2 glass) fiberglass	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:04
10	2436	(novich robertson velpari wu) and (((fiber filament) near2 glass) fiberglass)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:04
1	4	"9944960"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:05
11	253480	circuit adj board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:06
12	57150	pcb	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:06
13	280422	(circuit adj board) pcb	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:08

14	2764	(novich robertson velpari wu) and ((circuit adj board) pcb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:09
15	190	((novich robertson velpari wu) and (((fiber filament) near2 glass) fiberglass)) and ((novich robertson velpari wu) and ((circuit adj board) pcb))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:09
16	65466	inorganic near2 (particle particulate filler)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:10
17	23	((novich robertson velpari wu) and (((fiber filament) near2 glass) fiberglass)) and ((novich robertson velpari wu) and ((circuit adj board) pcb))) and (inorganic near2 (particle particulate filler))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:18
18	274	(inorganic near2 (particle particulate filler)) near matrix	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:20
19	25992	boron adj nitride	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:20
20	1	dichalcognide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:20
21	41074	boric adj acid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:21
22	20	chalcognide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:22
23	66387	(boron adj nitride) dichalcognide (boric adj acid) chalcognide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:22
24	10	((inorganic near2 (particle particulate filler)) near matrix) and ((boron adj nitride) dichalcognide (boric adj acid) chalcognide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/16 17:22

try this search w/ fillers of class 35 + 38

+ expansible clay

(X-search w/ fiber glass, pcb, etc.... if needed)